2SK3064

Silicon N-channel MOSFET

For switching circuit

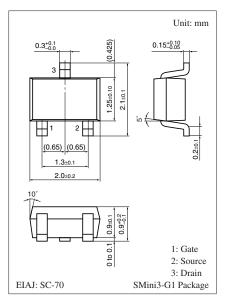
For rechargeable buttery pack (Li⁺ ion buttery, etc.)

■ Features

- ullet High gate-source voltage (Drain open) V_{GSO}
- ullet Low gate threshold voltage V_{th}

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Drain-source surrender voltage	V _{DSS}	30	V	
Gate-source voltage (Drain open)	V_{GSO}	±20	V	
Drain current	I_D	100	mA	
Peak drain current	I_{DP}	200	mA	
Power dissipation	P_{D}	150	mW	
Channel temperature	T_{ch}	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	



Marking symbol: 2D

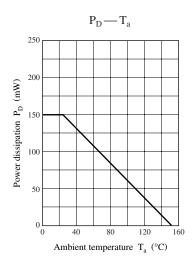
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

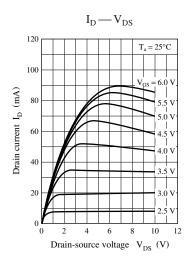
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source cutoff current	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			0.1	μΑ
Gate-source cutoff current	I_{GSS}	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±1.0	μΑ
Gate threshold voltage	V _{th}	$V_{DS} = 5 \text{ V}, I_{D} = 1 \mu A$	1.0		2.0	V
Forward transfer admittance	Y _{fs}	$V_{DS} = 5 \text{ V}, I_{D} = 10 \text{ mA}$	15			mS
ON resistance	R _{on}	$V_{GS} = 5 \text{ V}, I_{D} = 10 \text{ mA}$		30	50	Ω
Turn-on time	t _{on}	$V_{DD} = 5 \text{ V}, V_{GS} = 0 \text{ V to 5 V}$		150		ns
		$R_L = 200 \Omega$				
Turn-off time	t _{off}	$V_{DD} = 5 \text{ V}, V_{GS} = 5 \text{ V to } 0 \text{ V}$		35		ns
		$R_L = 200 \Omega$				

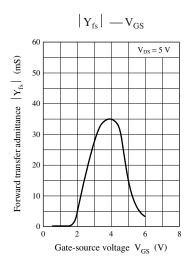
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

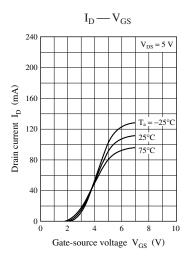
^{2.} Observe precautions for handling. Electrostatic sensitive devices.

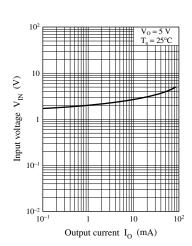
Panasonic











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